

#### 12V P-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C
-12V	14.8m $\Omega$ @ V <sub>GS</sub> = -4.5V	-9.5A
	$19m\Omega @ V_{GS} = -2.5V$	-8.5A
	$26m\Omega$ @ $V_{GS} = -1.8V$	-7.2A
	$32m\Omega @ V_{GS} = -1.5V$	-6.6A

# **Description**

This MOSFET is designed specifically for use in battery management applications.

## **Features**

- 0.6mm profile ideal for low profile applications
- PCB footprint of 4mm<sup>2</sup>
- Low Gate Threshold Voltage
- Fast Switching Speed
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

Case: U-DFN2020-6

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- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @4

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D 2

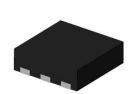
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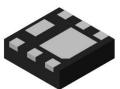
Weight: 0.0065 grams (Approximate)

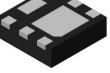
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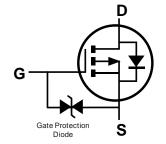
Top View





**Bottom View** 

Pin Out **Bottom View** 



Internal Schematic

# **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMP1022UFDF-7	U-DFN2020-6	3,000/Tape & Reel
DMP1022UFDF-13	U-DFN2020-6	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

U-DFN2020-6

# **Marking Information**



PU = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013)M = Month (ex: 9 = September)

Date Code Key

Year	2013	2014	20	15	2016	2017	2018	2019	20	20	2021	2022
Code	Α	В	(	)	D	Е	F	G	I	+	1	J
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V <sub>DSS</sub>	-12	V		
Gate-Source Voltage	V <sub>GSS</sub>	±8	V		
Continuos Durin Compant (Nata C) V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-9.5 -7.6	А
Continuous Drain Current (Note 6) V <sub>GS</sub> = -4.5V	t<5s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-11.0 -8.8	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I <sub>DM</sub>	-90	Α		
Continuous Source-Drain Diode Current	$T_A = +25$ °C $T_C = +25$ °C	Is	-2.5 -7.1	А	
Pulsed Source-Drain Diode Current (10µs pulse, duty	I <sub>SM</sub>	-50	Α		

## **Thermal Characteristics**

Characteristic		Symbol	Value	Units	
Total Bower Dissination (Note 5)	$T_A = +25^{\circ}C$	C	0.73	W	
Total Power Dissipation (Note 5)	$T_A = +70^{\circ}C$	$P_{D}$	0.47		
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	6	172	°C/W	
memai Resistance, Junction to Ambient (Note 5)	t<5s	$R_{\theta JA}$	128		
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	C	2.1	W	
Total Power Dissipation (Note 6)	$T_A = +70^{\circ}C$	$P_{D}$	1.3		
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	6	59	°C/W	
Thermal Resistance, Junction to Ambient (Note 6)	t<5s	$R_{\theta JA}$	45		
Thermal Resistance, Junction to Case (Note 6)	Steady state	$R_{ heta JC}$	5.1		
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C	

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

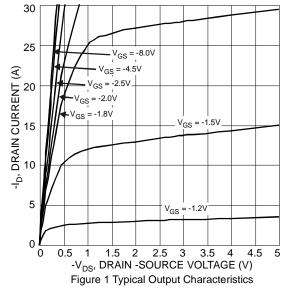
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-12	_	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	_	-200	nA	$V_{DS} = -12V, V_{GS} = 0V$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +55°C (Note 8)	I <sub>DSS</sub>	_	_	-2	μA	$V_{DS} = -12V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	-0.35	_	-0.8	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
			12	14.8		$V_{GS} = -4.5V, I_D = -4A$	
Static Drain-Source On-Resistance	D		15	19	mΩ	$V_{GS} = -2.5V, I_D = -4A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	20	26		$V_{GS} = -1.8V, I_{D} = -4A$	
			23	32		$V_{GS} = -1.5V, I_D = -2A$	
Diode Forward Voltage	$V_{SD}$	_	-0.8	-1.2	V	$V_{GS} = 0V, I_{S} = -8A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C <sub>iss</sub>	_	2,712	_		101/1/	
Output Capacitance	Coss	_	514	_	pF	$V_{DS} = -10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	467	_		1 – 1.01/11/12	
Gate Resistance	$R_g$	_	8.6	18	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge	Qg	_	48.3	_		$V_{GS} = -8V, V_{DS} = -6V, I_{D} = -10A$	
Total Gate Charge	Qg	_	28.6	_	nC	V 45V V 6V	
Gate-Source Charge	Q <sub>gs</sub>	_	4.2	_	l IIC	$V_{GS} = -4.5V, V_{DS} = -6V,$ $I_{D} = -10A$	
Gate-Drain Charge	$Q_{gd}$	_	7.0	_		ID = -10A	
Turn-On Delay Time	t <sub>D(on)</sub>	_	25.1	_			
Turn-On Rise Time	t <sub>r</sub>	_	39.8	_	ns	$V_{DS} = -6V, V_{GS} = -4.5V,$	
Turn-Off Delay Time	t <sub>D(off)</sub>	_	141	_		$R_G = 1\Omega$ , $I_D = -8A$	
Turn-Off Fall Time	t <sub>f</sub>	_	147	_			

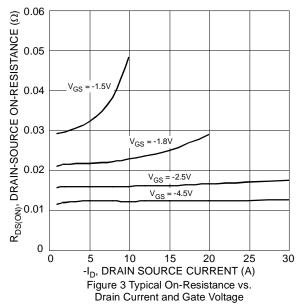
Notes:

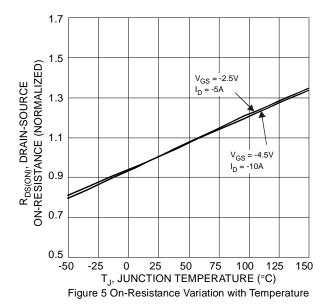
- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.

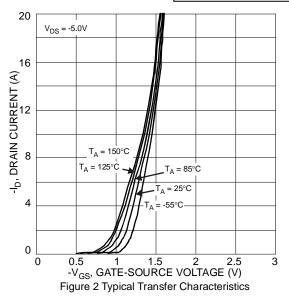


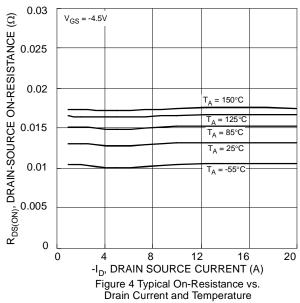












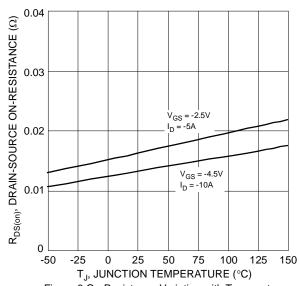
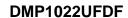


Figure 6 On-Resistance Variation with Temperature





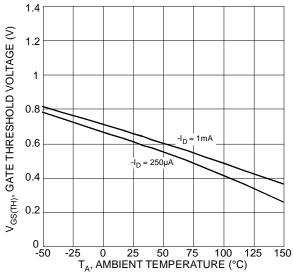
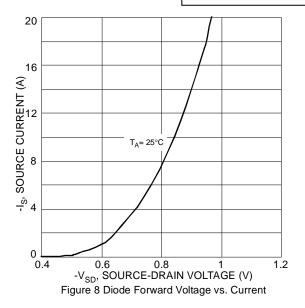
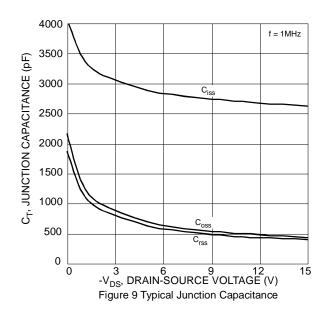
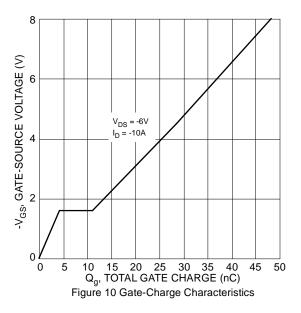
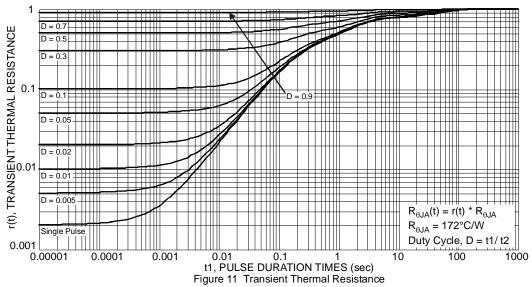


Figure 7 Gate Threshold Variation vs. Ambient Temperature





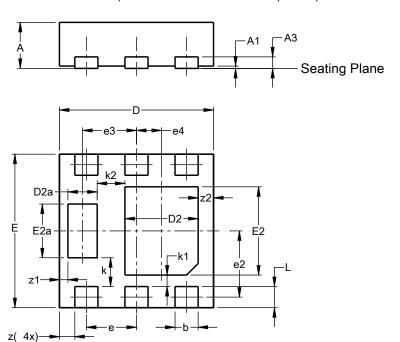






## **Package Outline Dimensions**

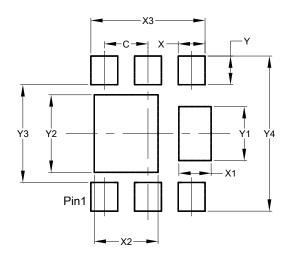
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



U-DFN2020-6								
(Type F)								
Dim	Min	Min Max Typ						
Α	0.57	0.63	0.60					
A1	0.00	0.05	0.03					
A3	-	-	0.15					
b	0.25	0.35	0.30					
D	1.95	2.05	2.00					
D2	0.85	1.05	0.95					
D2a	0.33	0.43	0.38					
Е	1.95	2.05	2.00					
E2	1.05	1.25	1.15					
E2a	0.65	0.75	0.70					
е	0.65 BSC							
e2	(	).863 BS	SC					
е3		0.70 BS	С					
e4	(	).325 BS	SC					
k	0.37 BSC							
k1	0.15 BSC							
k2	0.36 BSC							
L	0.225 0.325 0.275							
Z	0.20 BSC							
<b>z</b> 1	0.110 BSC							
<b>z2</b>	0.20 BSC							
All C	All Dimensions in mm							

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value				
Dimononono	(in mm)				
С	0.650				
Х	0.400				
X1	0.480				
X2	0.950				
Х3	1.700				
Υ	0.425				
Y1	0.800				
Y2	1.150				
Y3	1.450				
Y4	2.300				



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